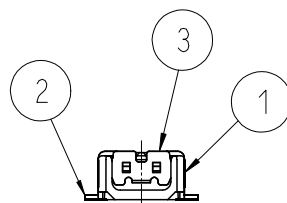
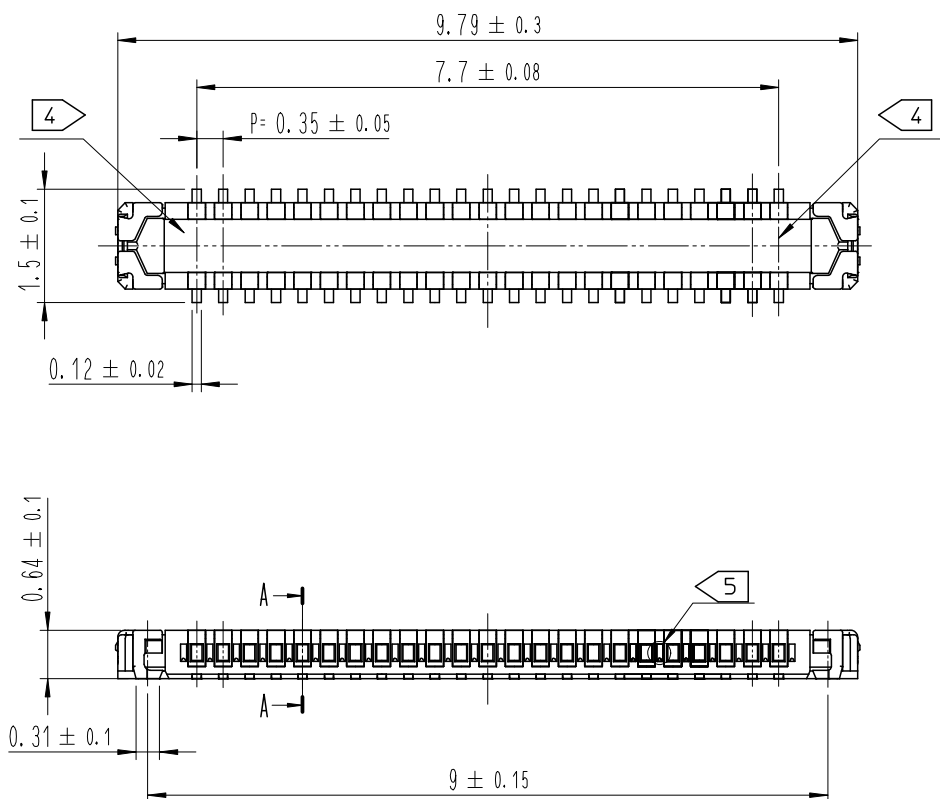


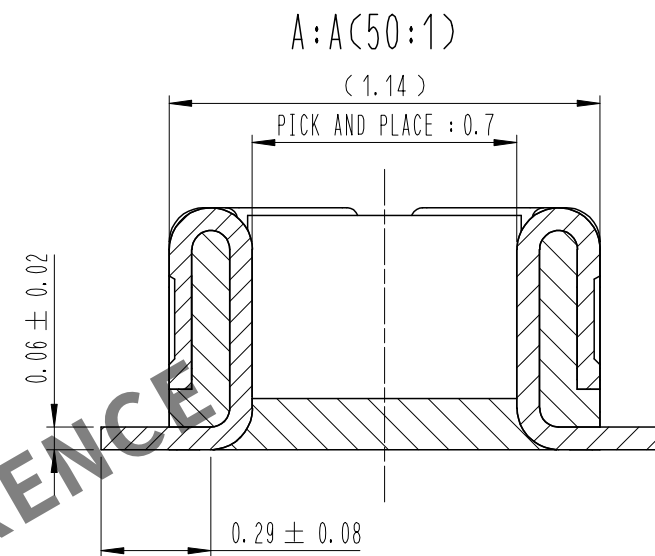
A
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E
F



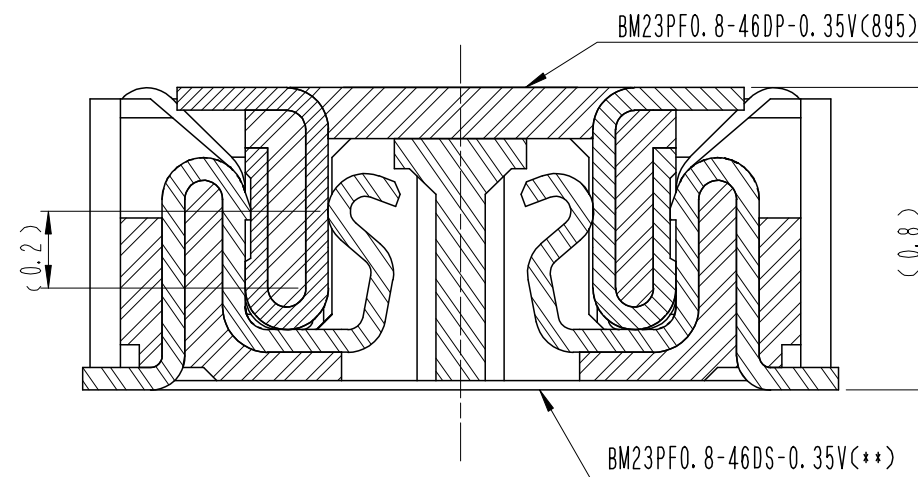
DRAWING FOR REFERENCE
This is subject to change without notice

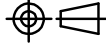
- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μm MIN.
SMT LEAD : GOLD 0.05 μm MIN.
UNDER PLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5. A PART OF THE WALL COULD BE NOTCHED.

5					6					7					8				
	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS			擔當 B Y	檢圖 CHKD	年月日 DATE			△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS			擔當 B Y	檢圖 CHKD	年月日 DATE			
△							. .		△							. .			
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ENGAGEMENT FIGURE (50:1)

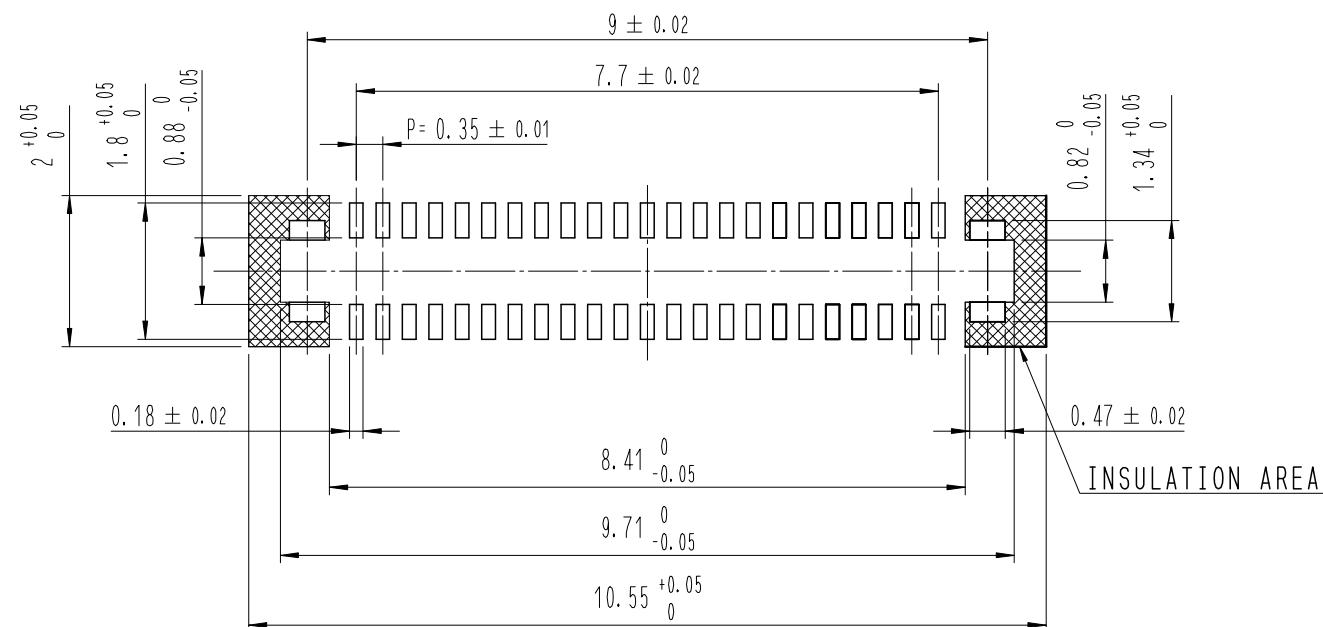


4	PS	CLEAR (EMBOSSED CARRIER TAPE)					
3	COPPER ALLOY	3					
2	COPPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)		
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)		
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS		
REMARKS			DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
			S. H. JUNG 17. 05. 09	S. H. JUNG 17. 05. 09	H. W. JO 17. 05. 09	T. S. KANG 17. 05. 09	17. 05. 09
CODE NO. (OLD)		DRAWING NO.	PART NO.				
	SCALE	EDC3-632257	BM23PF0.8-46DP-0.35V(895)				
	10:1	 HIROSE KOREA CO., LTD.	CODE NO		CL 6644-0088-5-895		
UNITS			1/3				

A
B
C
D
E
F

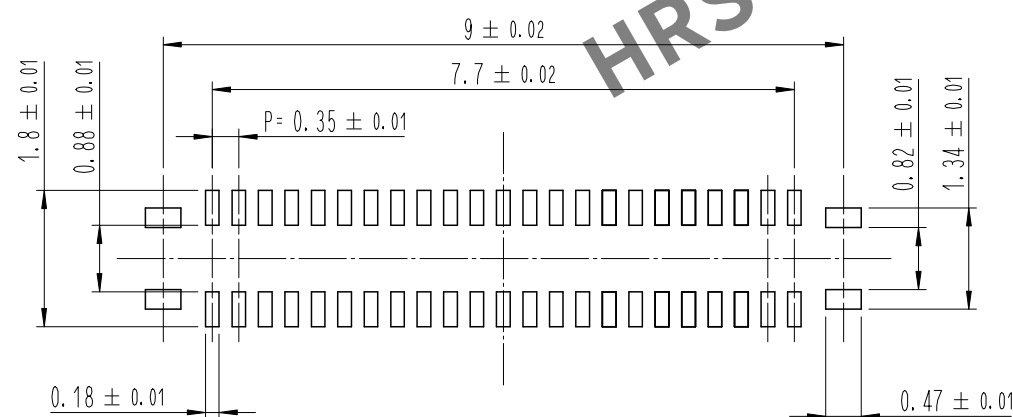
May.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

7 RECOMMENDED PCB LAYOUT

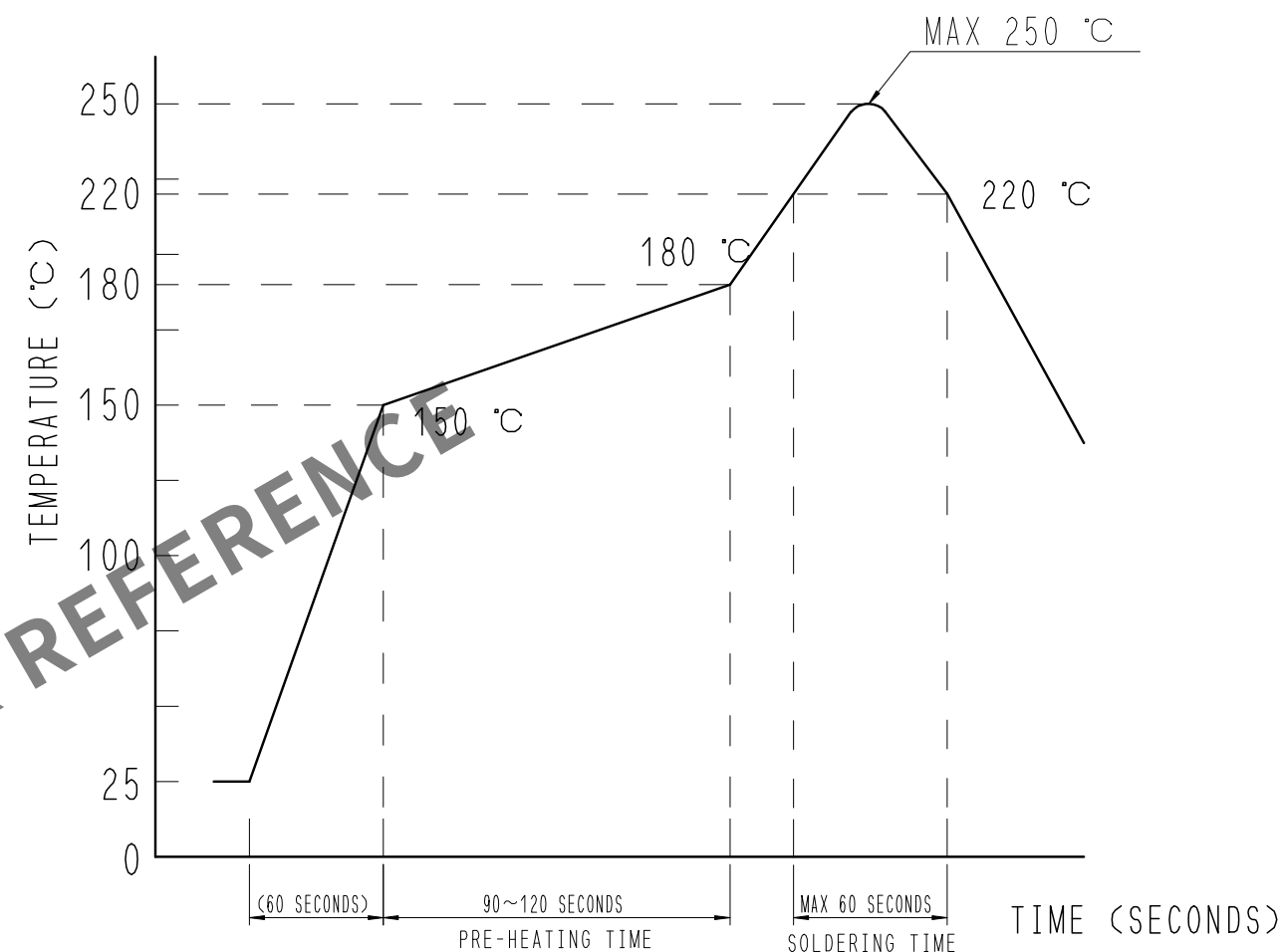


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C : 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632257	PART NO.	BM23PF0.8-46DP-0.35V(895)
	SCALE	10:1	CODE NO	CL 6644-0088-5-895
	UNITS	mm		

HIROSE KOREA CO., LTD.

